

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A method for producing an aluminum/ceramic bonding substrate, said method comprising the steps of:

causing ~~an~~ a solid aluminum member having a purity of 99.5 % or more to contact at least one side of a ceramic substrate; and

thereafter, heating the solid aluminum member and the ceramic substrate, which contacts the solid aluminum member, at a temperature of 620 to 650 °C in an inert gas to bond the solid aluminum member directly to the ceramic substrate.

Claim 2 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said ceramic substrate is a ceramic substrate containing aluminum nitride as a principal component.

Claim 3 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said ceramic substrate is a ceramic substrate containing alumina as a principal component.

Claim 4 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said purity of said aluminum member is 99.9 % or more.

Claim 5 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said inert gas is nitrogen gas.

Claim 6 (currently amended): An aluminum/ceramic bonding substrate comprising:

a ceramic substrate; and

~~an~~ a solid aluminum member having a purity of 99.5 % or more, said solid aluminum member ~~contacting~~ being bonded directly to at least one side of said ceramic substrate ~~to be bonded directly thereto by heating the solid aluminum member and the ceramic substrate after causing the solid aluminum member to contact the ceramic substrate,~~

wherein a peel strength between said solid aluminum member and said ceramic substrate is 49 N/cm or more.

Claim 7 (original): An aluminum/ceramic bonding substrate as set forth in claim 6, wherein said ceramic substrate is a ceramic substrate containing aluminum nitride as a principal component.

Claim 8 (original): An aluminum/ceramic bonding substrate as set forth in claim 6, wherein said ceramic substrate is a ceramic substrate containing alumina as a principal component.

Claim 9 (original): An aluminum/ceramic bonding substrate as set forth in claim 6, wherein said purity of said aluminum member is 99.9 % or more.

Claim 10 (original): A power module using an aluminum/ceramic bonding substrate as set forth in claim 6.